

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231  <b>INFORMATION DISCLOSURE          STATEMENT BY APPLICANT</b>	ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
	Applicant Lee, Teck Kheng	Confirmation No. 7687
	Filing Date January 16, 2002	Group Art Unit 2813

## U.S. PATENT DOCUMENTS

Examiner Initials		Patent/Publication Number	Publication Date	Patentee or Applicant	U.S. Class	Sub-Class
<i>[Signature]</i>	A1	6,281,046 B1	08/28/01	Lam	438	113
	A2	6,239,496 B1	05/29/01	Asada	257	777
	A3	6,180,881 B1	01/30/01	Isaak	174	52.4
	A4	5,844,315	12/01/98	Melton et al.	257	738
	A5	5,608,265	03/04/97	Kitano et al.	257	738
<i>[Signature]</i>	A6	4,954,875	09/04/90	Clements	357	75

## OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initials		Non-Patent Document
<i>[Signature]</i>		Australian Search Report dated 03 November 2004 (5 pages).

Examiner Initials	<i>[Signature]</i>	Date Considered	2/2/05
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

**Title of  
Invention**


**Elimination of RDL Using Tape Base Flip Chip on Flex for Die  
Stacking**

Application Number : 10/050507  
Confirmation Number: 7687  
First Named Applicant: Teck Lee  
Attorney Docket Number: MTI-31607  
Art Unit: 2813  
Examiner: Jack SJ Chen  
Search string: ( 6308525 or 5468995 or 6610559 ).pn



## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6308525	2001-03-27	Imasu et al.		361	783
	2	5468995	1995-11-21	Higgins III		257	697
	3	6610559	2003-08-26	Wang et al.		438	108

**Signature**

Examiner Name	Date
	2/2/06

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Stylesheet Version v18.0

**Title of  
Invention**



Elimination of RDk Using Tape Base Flip Chip on Flex for Die  
Stacking

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First Named Applicant: Teck Lee  
Attorney Docket Number: MTI-31607  
Art Unit: 2813  
Examiner: Jack SJ Chen  
Search string: ( 4415403 or 6847105 ).pn

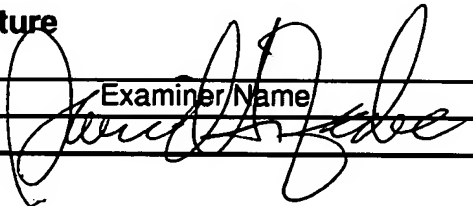
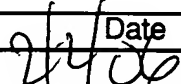


## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4415403	1983-11-15	Bakewell		216	27
	2	6847105	2005-01-25	Koopmans		257	686

**Signature**

	Examiner Name		Date
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Elimination of RDL Using Tape Base Flip Chip on Flex for Die  
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Art Unit: 2813  
Examiner: Jack SJ Chen  
Search string: ( 6624060 or 20020027080 or 20030134450 ).pn



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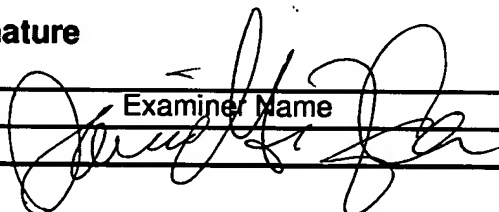
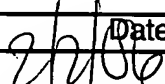
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6624060	2003-09-23	Chen et al.		438	613

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020027080	2002-03-07	Yoshioka et al.	A1	205	123
	2	20030134450	2003-07-17	Lee	A1	438	106

## Signature

	Examiner Name		Date
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